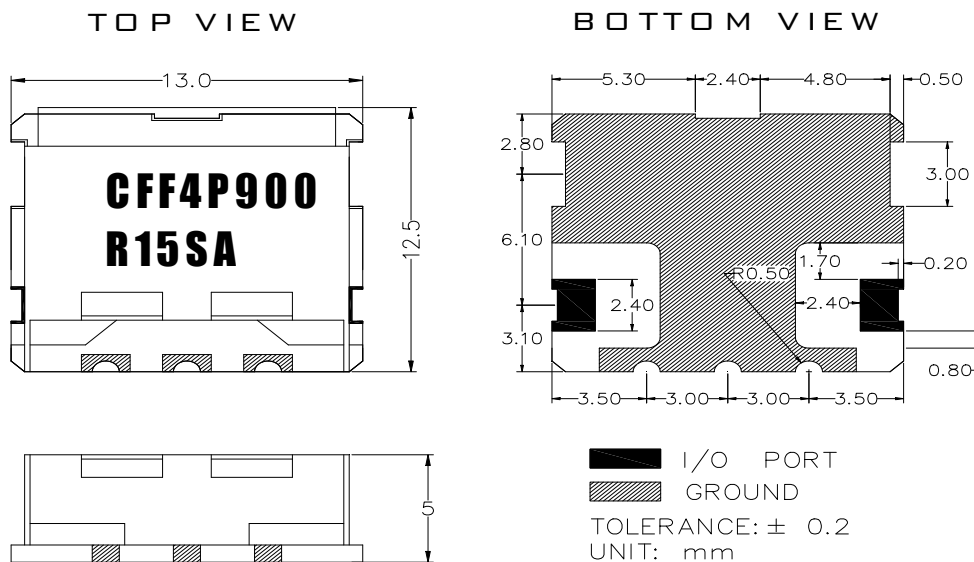


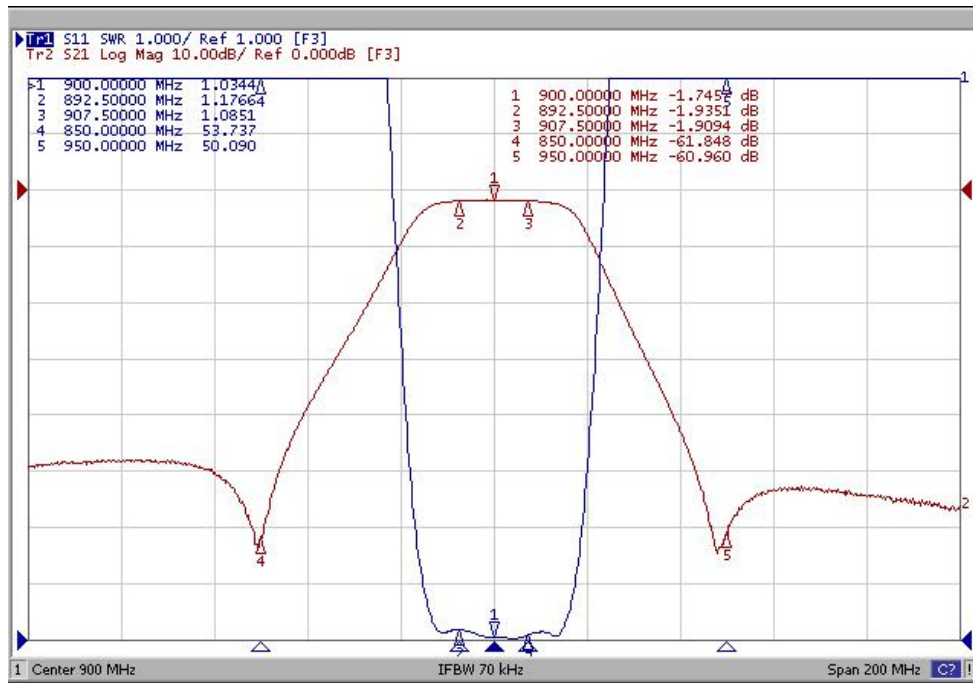
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	900.0	MHz
Bandwidth [BW]	$f_{o\pm 7.5}$ [892.5 ~907.5]	MHz
Insertion Loss in BW	3.0	dB max
Ripple in BW	0.5	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	60 dB min. @ $f_{o\pm 50}$	MHz
	dB min @ $f_{o\pm}$ [&]	MHz
	dB min @ $f_{o\pm}$ [&]	MHz
	dB min @ $f_{o\pm}$ [~]	MHz
Group Delay Variation		ns max
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

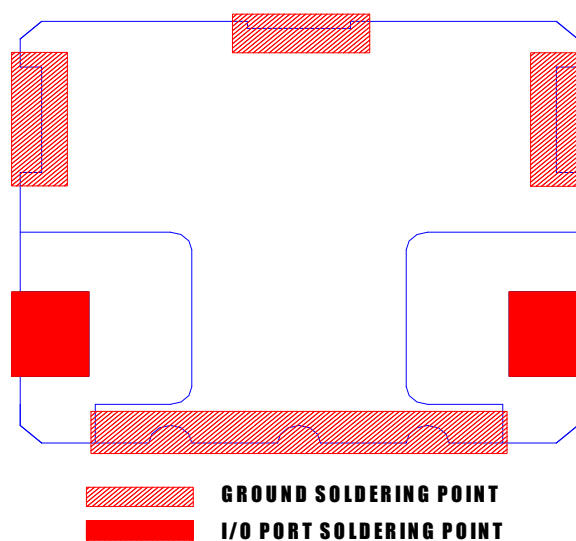
Mechanical Specification



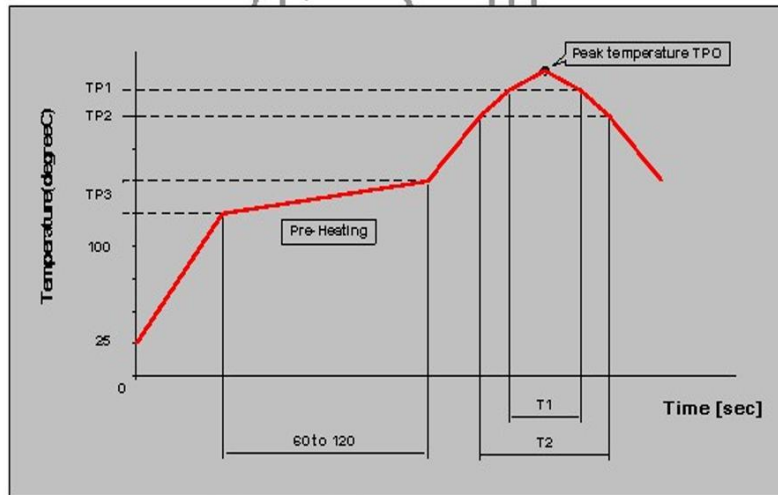
 Plot Data



 Recommended PC Board Pattern



 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±/±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180